

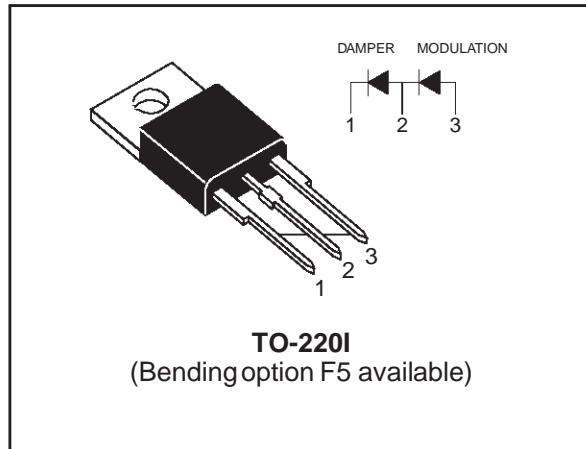
DAMPER + MODULATION DIODE FOR VIDEO

MAIN PRODUCT CHARACTERISTICS

| | MODUL | DAMPER |
|-------------|-------|--------|
| $I_{F(AV)}$ | 5 A | 5 A |
| V_{RRM} | 600 V | 1500 V |
| t_{rr} | 95 ns | 300 ns |
| V_F | 1.3 V | 1.5 V |

FEATURES AND BENEFITS

- FULL KIT IN ONE PACKAGE
- DMV16 IS SUITED FOR 16kHz TV's
- OUTSTANDING PERFORMANCE OF TURBOSWITCH™ "A" AS MODULATION AND LEADING EDGE PLANAR PLATINUM DAMPER
- LEAD BENDING OPTION AVAILABLE
- INSULATED PACKAGE (2500 V_{RMS})



DESCRIPTION

High voltage semiconductor especially designed for horizontal deflection stage in standard and high resolution video display with E/W correction.

The TO-220I insulated package includes both the DAMPER diode and the MODULATION diode. Assembled on automated line and UL recognized. Best insulating and dissipating characteristics, thanks to the internal ceramic insulation layer.

ABSOLUTE RATINGS

| Symbol | Parameter | VALUE | | Unit | |
|-------------|--|---------------|--------|------|--|
| | | MODUL | DAMPER | | |
| V_{RRM} | Repetitive peak reverse voltage | 600 | 1500 | V | |
| $I_{F(AV)}$ | Forward average current | 5 | 5 | A | |
| I_{FSM} | Surge non repetitive forward current | | | | |
| T_{stg} | Storage temperature range | - 40 to + 150 | | °C | |
| T_j | Maximum operating junction temperature | 150 | | | |

DMV16

ELECTRICAL CHARACTERISTICS OF THE DAMPER DIODES OF THE DMV16

| Symbol | Parameter | Test Conditions | | Typ. | Max. | Unit |
|----------|-------------------------|--|---|------|------------|---------|
| I_R * | Reverse leakage current | $V_R = V_{RRM}$ | $T_j = 25^\circ C$ $T_j = 125^\circ C$ | | 60 500 | μA |
| V_F ** | Forward voltage drop | $I_F = 5 A$ | $T_j = 25^\circ C$ $T_j = 125^\circ C$ | 1.0 | 1.6 1.5 | V |
| t_{rr} | Reverse recovery time | $I_F = 1 A \quad dI_F/dt = -50 A/\mu s$ $V_R = 30 V$ | $T_j = 25^\circ C$ | 200 | 300 | ns |
| | | $I_F = 100 mA \quad I_R = 100 mA$ $I_{RR} = 10mA$ | | 1500 | | |
| t_{fr} | Forward recovery time | $I_F = 5 A \quad dI_F/dt = 80 A/\mu s$ Measured at $V_{FR} = 3 V$ | $T_j = 100^\circ C$ | 350 | | ns |
| V_{FP} | Peak forward voltage | | | 25 | 34 | V |

Pulse test : * $t_p = 5 ms, \delta < 2\%$

** $t_p = 380 \mu s, \delta < 2\%$

To evaluate the maximum conduction losses use the following equations:

$$P = 1.14 \times I_{F(AV)} + 0.072 \times I_F^2(\text{RMS})$$

ELECTRICAL CHARACTERISTICS OF THE MODULATION DIODE OF THE DMV16

| Symbol | Parameter | Test Conditions | | Typ. | Max. | Unit |
|----------|-------------------------|--|---|------|------------|---------|
| I_R * | Reverse leakage current | $V_R = 480V$ | $T_j = 25^\circ C$ $T_j = 125^\circ C$ | 150 | 20 500 | μA |
| V_F ** | Forward voltage drop | $I_F = 3A$ | $T_j = 25^\circ C$ $T_j = 125^\circ C$ | | 1.4 1.3 | V |
| t_{rr} | Reverse recovery time | $I_F = 1A \quad dI_F/dt = -50A/\mu s$ $V_R = 30V$ | $T_j = 25^\circ C$ | | 95 | ns |
| | | $I_F = 100mA \quad I_R = 100mA$ $I_{RR} = 10mA$ | | 210 | | |
| t_{fr} | Forward recovery time | $I_F = 3A \quad dI_F/dt = 80A/\mu s$ Measured at $V_{FR} = 1.1 \times V_F$ (max) | $T_j = 100^\circ C$ | | 500 | ns |
| V_{FP} | Peak forward voltage | | | | 8 | V |

To evaluate the maximum conduction losses use the following equations :

$$P = 1.06 \times I_{F(AV)} + 0.08 \times I_F^2(\text{RMS})$$

Pulse test : * $t_p = 5 ms, \delta < 2\%$
** $t_p = 380 \mu s, \delta < 2\%$

THERMAL RESISTANCES

| Symbol | Parameter | Max. | Unit |
|---------------|---|------|------|
| $R_{th(j-c)}$ | Damper junction to case | 5 | °C/W |
| $R_{th(j-c)}$ | Modulation junction to case | 5.5 | |
| $R_{th(c)}$ | Coupling | 0.2 | |
| $R_{th(j-c)}$ | Total as per full $I_{F(AV)}$ maximum ratings | 5.3 | |

ORDERING INFORMATION

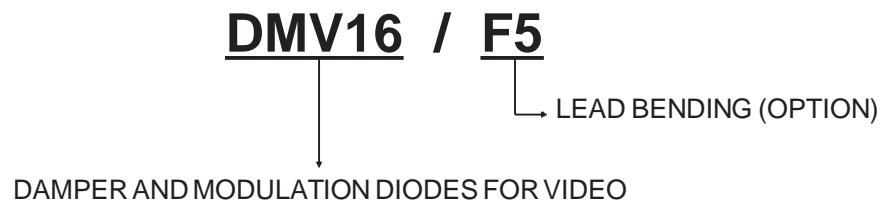


Fig. 1-1: Power dissipation versus peak forward current (triangular waveform, $\delta=0.45$) (damper diode.)

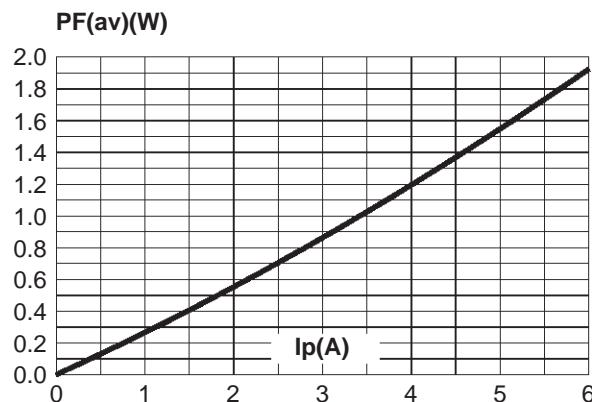


Fig. 1-2: Power dissipation versus peak forward current (triangular waveform, $\delta=0.45$) (modulation diode)

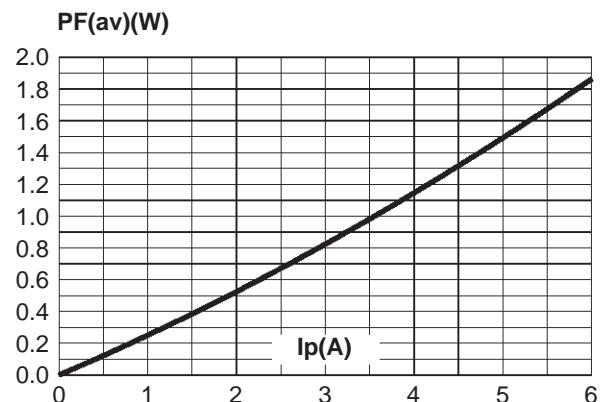
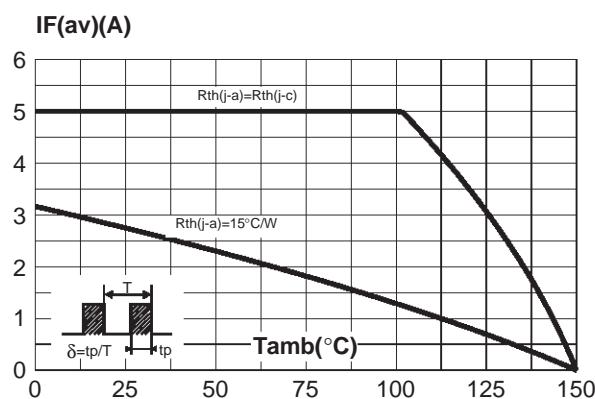


Fig. 2: Average forward current versus ambient temperature.



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Fig. 3-1: Forward voltage drop versus forward current (damper diode).

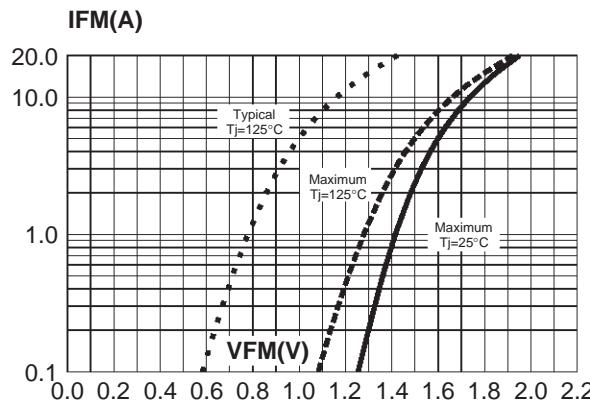


Fig. 3-2: Forward voltage drop versus forward current (modulation diode).

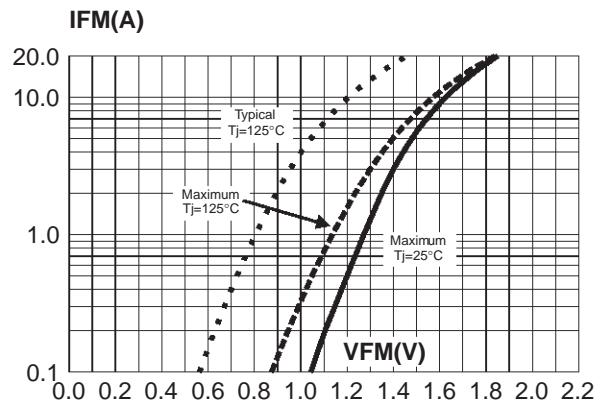


Fig. 4: Relative variation of thermal impedance junction to case versus pulse duration.

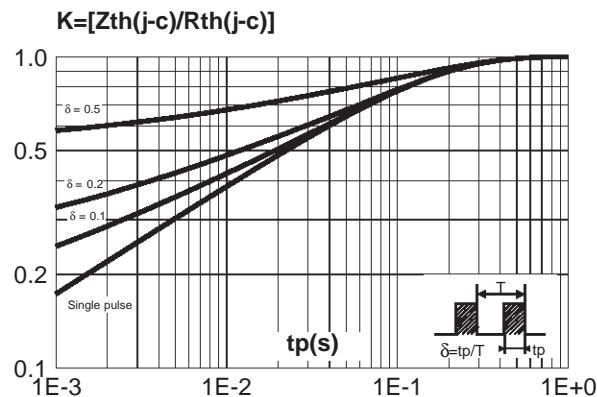


Fig. 5-2: Non repetitive surge peak forward current versus overload duration (modulation diode).

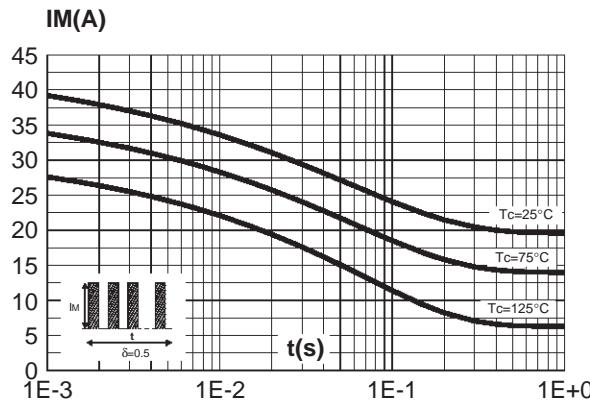


Fig. 5-1: Non repetitive surge peak forward current versus overload duration (damper diode).

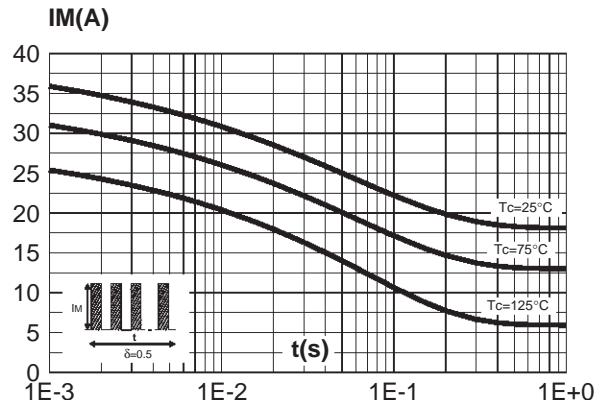


Fig. 6-1: Reverse recovery charges versus dIF/dt (damper diode).

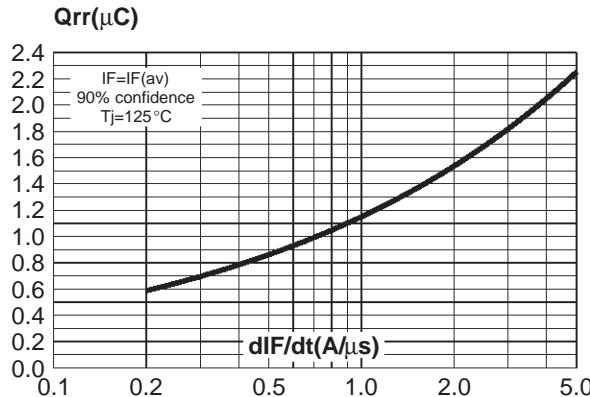


Fig. 6-2: Reverse recovery charges versus dIF/dt (modulation diode).

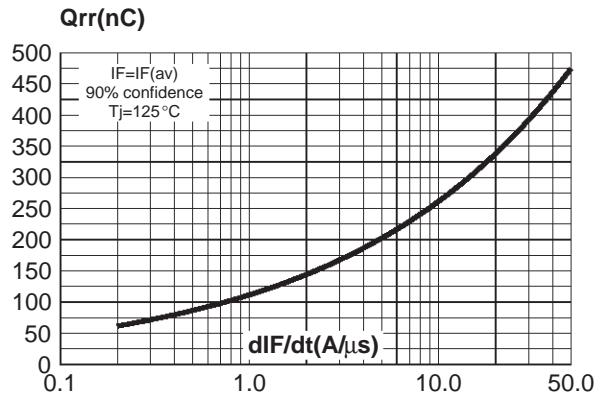


Fig. 7-1: Reverse recovery current versus dIF/dt (damper diode).

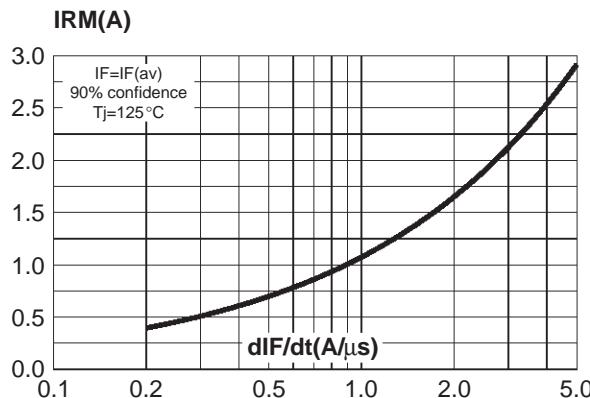


Fig. 7-2: Reverse recovery current versus dIF/dt (modulation diode).

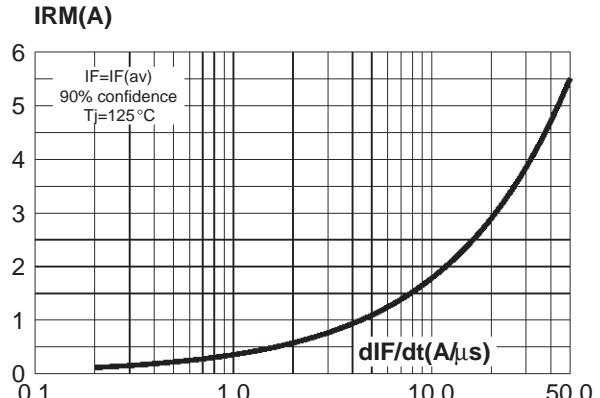


Fig. 8-1: Transient peak forward voltage versus dIF/dt (damper diode).

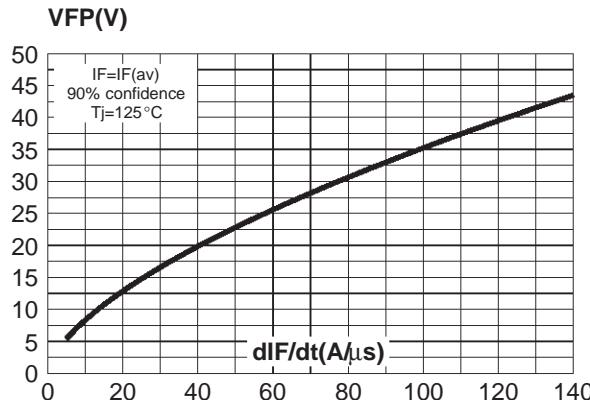
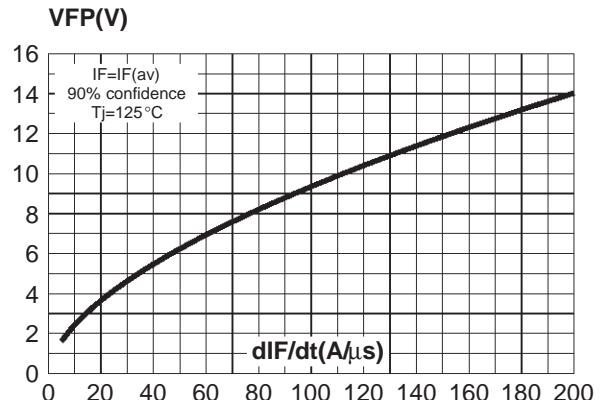


Fig. 8-2: Transient peak forward voltage versus dIF/dt (modulation diode).



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Fig. 9-1: Forward recovery time versus dIF/dt (damper diode).

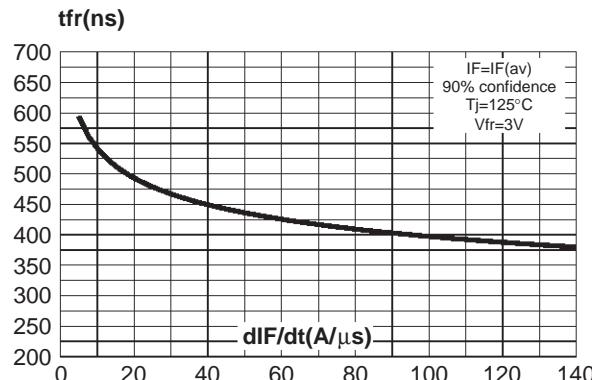


Fig. 9-2: Forward recovery time versus dIF/dt (modulation diode).

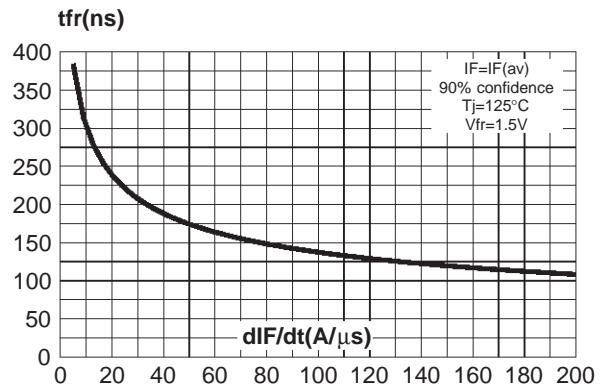


Fig. 10: Dynamic parameters versus junction temperature.

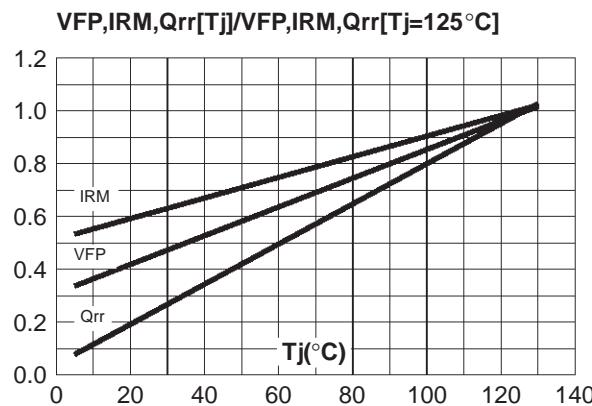
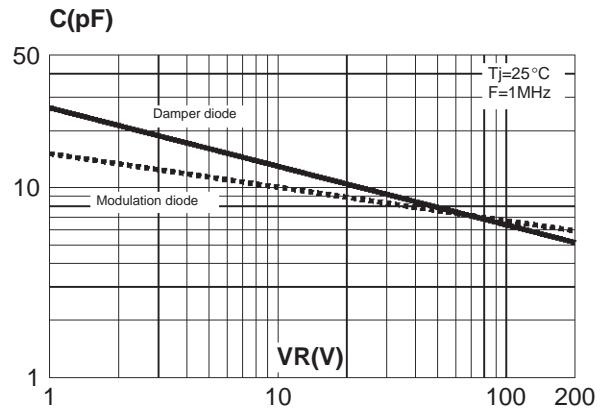
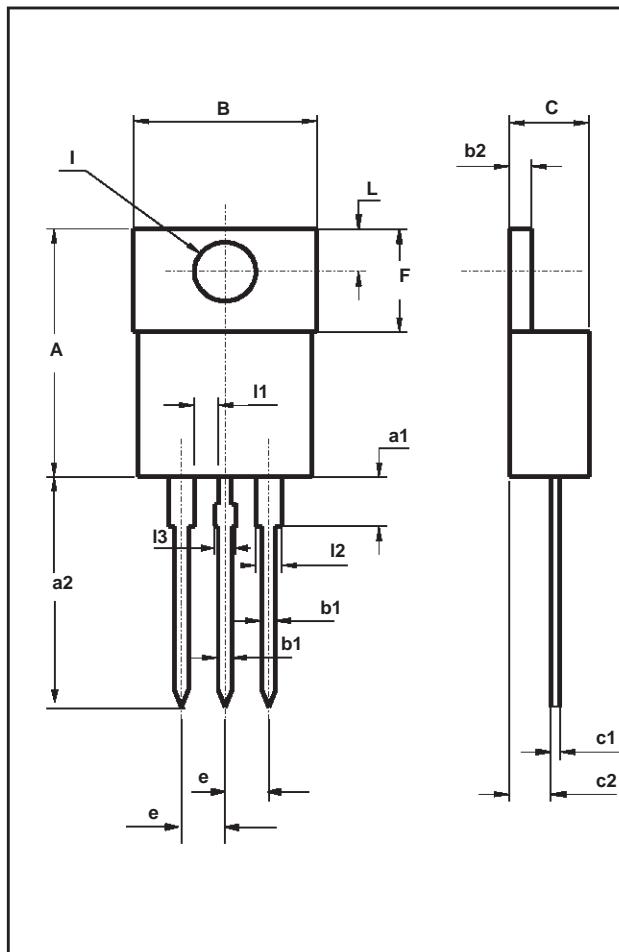


Fig. 11: Junction capacitance versus reverse voltage applied (typical values).



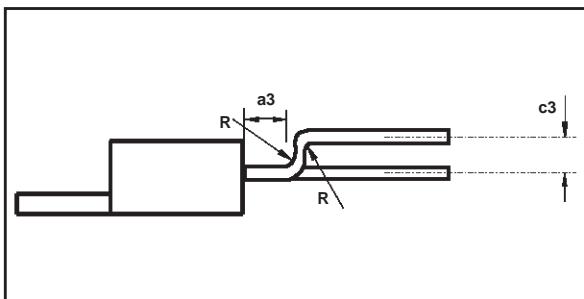
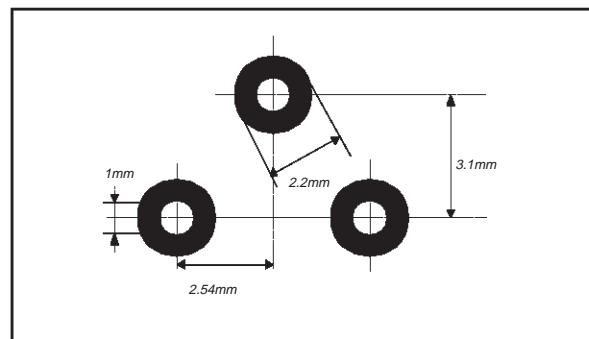
PACKAGE MECHANICAL DATA
TO-220I



| REF. | DIMENSIONS | | | |
|------|-------------|-------|--------|-------|
| | Millimeters | | Inches | |
| | Min. | Max. | Min. | Max. |
| A | 15.07 | 15.32 | 0.593 | 0.603 |
| a1 | | 4.50 | | 0.177 |
| a2 | 12.70 | 14.70 | 0.500 | 0.579 |
| B | 10.20 | 10.45 | 0.402 | 0.411 |
| b1 | 0.64 | 0.96 | 0.025 | 0.038 |
| b2 | 1.15 | 1.39 | 0.045 | 0.055 |
| C | 4.48 | 4.82 | 0.176 | 0.190 |
| c1 | 0.35 | 0.65 | 0.020 | 0.026 |
| c2 | 2.10 | 2.70 | 0.083 | 0.106 |
| e | 2.29 | 2.79 | 0.090 | 0.110 |
| F | 5.85 | 6.85 | 0.230 | 0.270 |
| I | 3.55 | 4.00 | 0.140 | 0.157 |
| L | 2.56 | 2.67 | 0.100 | 0.101 |
| I1 | 1.30 | | 0.051 | |
| I2 | 1.45 | 1.75 | 0.057 | 0.069 |
| I3 | 0.80 | 1.20 | 0.031 | 0.047 |

BENDING OPTION "F5"

Recommended for high voltage layout clearance

**PRINTED CIRCUIT LAYOUT FOR F5 LAYOUT**

| REF. | DIMENSIONS | | | |
|------|-------------|------|-----------|-------|
| | Millimeters | | Inches | |
| | Min. | Max. | Min. | Max. |
| a3 | 1.65 | 2.41 | 0.065 | 0.095 |
| c3 | 2.92 | 3.30 | 0.115 | 0.130 |
| R | 1.00 typ. | | 1.00 typ. | |

- **Marking:** Type number
- Cooling method: C
- Weight: 2.3 g
- Recommended torque value: 0.8 m.N.
- Maximum torque value: 1 m.N.
- Epoxy meets UL94,V0
- Capacitance: 7 pF
- Shipped: 50 units per tube

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